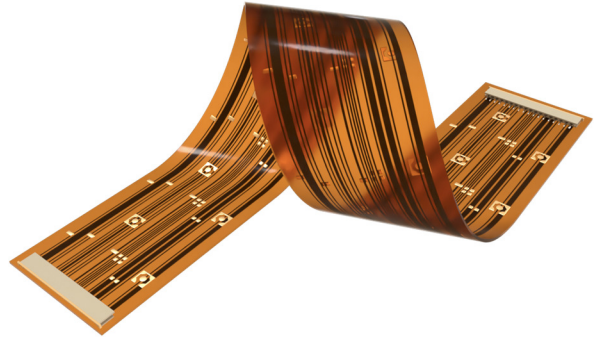


Circuit Boards can be flexible but our quality isn't



Features	Standard	Advanced
Number of Layers	1-4 Layers	10 Layers
Base Material	Polyimide (PI)	Polyimide (PI), Epoxy, BT, PET, PTFE
Maximum Board Thickness	0.65mm	0.75mm
Minimum Board Thickness	0.075mm	0.05mm
Board Thickness Tolerance	±0.05mm	±0.03mm
Base Copper Thickness	9um, 12um 35um	6um, 18um, 70um
Insulation Thickness	15 - 45um	12 - 50um
Panel Size of Board	Minimum: 30 x 30mm	Minimum: 10 x 15mm
	Maximum: 450 x 350mm	Maximum: 650 x 600mm
Minimum Drill Hole	0.05mm	0.02mm
Minimum Track Width / Spacing	0.05mm / 0.05mm	0.035mm / 0.035mm
Outline Tolerance	±0.1mm	±0.05mm
Surface Finishing	Electroless Nickel Immersion Gold (ENIG), Electrolytic Nickel and Gold, Electrolytic Tin, Immersion Tin, OSP	
Cover Materials	Polyimide (PI); Liquid Photo Imageable (LPI)	
Stiffener Materials	Polyimide (PI), FR-4, Steel Plate	
Additional Processes	Adhesive Tape; EMI Shielding	
Acceptance Standard	IPC-6013 Class 2 or Class 3	
Profiling Method	Laser Cutting, Punching, Routing	